32,768-word × 8-bit High Speed CMOS Static RAM

HITACHI

ADE-203-135D (Z) Rev. 4.0 Nov. 29, 1995

Description

The Hitachi HM62256B is a CMOS static RAM organized 32-kword \times 8-bit. It realizes higher performance and low power consumption by employing 0.8 μ m Hi-CMOS process technology. The device, packaged in 8 \times 14 mm TSOP, 8 \times 13.4 mm TSOP with thickness of 1.2 mm, 450-mil SOP (foot print pitch width), 600-mil plastic DIP, or 300-mil plastic DIP, is available for high density mounting. It offers low power standby power dissipation; therefore, it is suitable for battery back-up systems.

Features

High speed

Fast access time: 45/55/70/85 ns (max)

· Low power

Standby: 1.0 µW (typ)

Operation: 25 mW (typ) (f = 1 MHz)

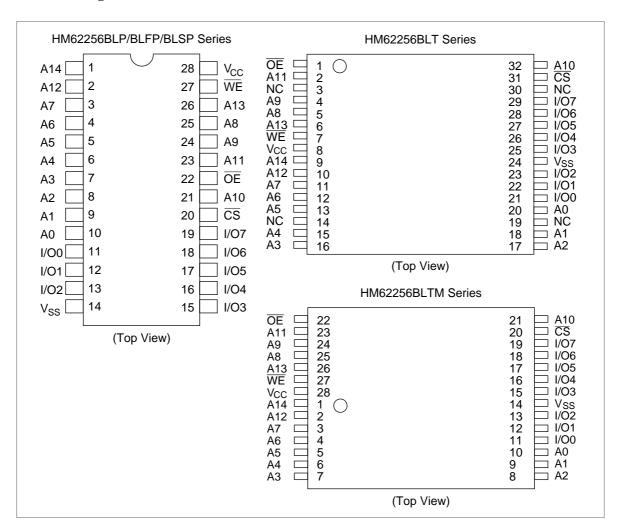
- Single 5 V supply
- Completely static memory
 No clock or timing strobe required
- · Equal access and cycle times
- Common data input and output Three state output
- Directly TTL compatible All inputs and outputs
- · Capability of battery back up operation

Ordering Information

Type No.	Access Time	Package
HM62256BLP-7	70 ns	600-mil 28-pin plastic DIP (DP-28)
HM62256BLP-7SL	70 ns	_
HM62256BLSP-7	70 ns	300-mil 28-pin plastic DIP (DP-28NA)
HM62256BLSP-7SL	70 ns	_
HM62256BLFP-7T	70 ns	450-mil 28-pin plastic SOP (FP-28DA)
HM62256BLFP-4SLT ^{*1} HM62256BLFP-5SLT HM62256BLFP-7SLT	45 ns 55 ns 70 ns	_
HM62256BLFP-7ULT	70 ns	_
HM62256BLT-8	85 ns	8 mm × 14 mm 32-pin TSOP (TFP-32DA)
HM62256BLT-7SL	70 ns	_
HM62256BLTM-8	85 ns	8 mm × 13.4 mm 28-pin TSOP (TFP-28DA)
HM62256BLTM-4SL ^{*1} HM62256BLTM-5SL HM62256BLTM-7SL	45 ns 55 ns 70 ns	-
HM62256BLTM-7UL	70 ns	

Note: 1. Under development

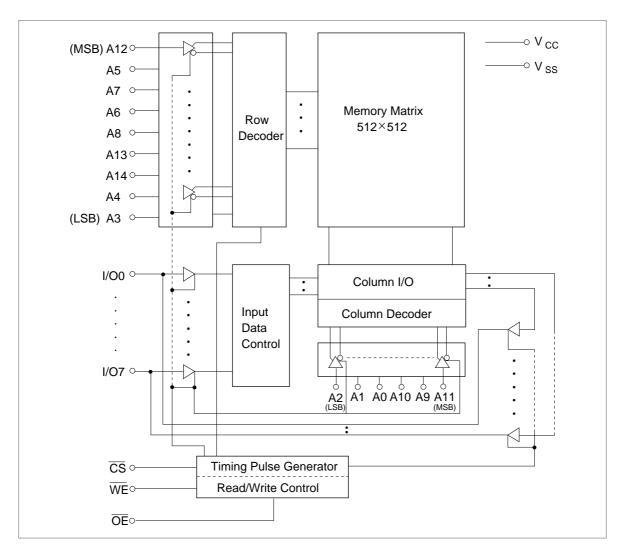
Pin Arrangement



Pin Description

Symbol	Function
A0 – A14	Address
I/O0 – I/O7	Input/output
CS	Chip select
WE	Write enable
ŌĒ	Output enable
NC	No connection
V _{cc}	Power supply
V _{SS}	Ground

Block Diagram



Function Table

WE	CS	ŌĒ	Mode	V _{cc} Current	I/O Pin	Ref. Cycle
Χ	Н	Х	Not selected	I _{SB} , I _{SB1}	High-Z	_
Н	L	Н	Output disable	I _{cc}	High-Z	
Н	L	L	Read	I _{cc}	Dout	Read cycle (1)–(3)
L	L	Н	Write	I _{cc}	Din	Write cycle (1)
L	L	L	Write	I _{cc}	Din	Write cycle (2)

Note: X: H or L

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Power supply voltage ^{*1}	V _{cc}	−0.5 to +7.0	V	
Terminal voltage ^{*1}	V _T	-0.5^{*2} to $V_{CC} + 0.3^{*3}$	V	
Power dissipation	P _T	1.0	W	
Operating temperature	Topr	0 to + 70	°C	
Storage temperature	Tstg	-55 to +125	°C	
Storage temperature under bias	Tbias	-10 to +85	°C	

Notes: 1. Relative to V_{ss}

2. V_T min: -3.0 V for pulse half-width ≤ 50 ns

3. Maximum voltage is 7.0 V

Recommended DC Operating Conditions (Ta = $0 \text{ to } +70^{\circ}\text{C}$)

Parameter	Symbol	Min	Тур	Max	Unit	
Supply voltage	V _{cc}	4.5	5.0	5.5	V	
	V _{SS}	0	0	0	V	
Input high (logic 1) voltage	V_{IH}	2.2	_	V _{cc} +0.3	V	
Input low (logic 0) voltage	V _{IL}	-0.5 *1	_	0.8	V	

Note: 1. V_{IL} min: -3.0 V for pulse half-width ≤ 50 ns

DC Characteristics (Ta = 0 to +70°C,
$$V_{CC}$$
 = 5 V ±10%, V_{SS} = 0 V)

Parameter		Symbol	Min	Typ*1	Max	Unit	Test Conditions
Input leakage current		ILI	_	_	1	μΑ	$Vin = V_{SS}$ to V_{CC}
Output leakage current		I _{LO}	_	_	1	μΑ	$\overline{\text{CS}} = \text{V}_{\text{IH}} \text{ or } \overline{\text{OE}} = \text{V}_{\text{IH}} \text{ or } \overline{\text{WE}} = \text{V}_{\text{IL}},$ $\text{V}_{\text{SS}} \leq \text{V}_{\text{I/O}} \leq \text{V}_{\text{CC}}$
Operating power supply current		I _{cc}		6	15	mA	$\overline{\text{CS}} = \text{V}_{\text{IL}}$ others = $\text{V}_{\text{IH}}/\text{V}_{\text{IL}}$ $\text{I}_{\text{I/O}} = 0 \text{ mA}$
Average operating power supply current	HM62256B-4	I _{CC1}			70	mA	min cycle, duty = 100 %, $I_{I/O} = 0$ mA $\overline{CS} = V_{IL}$, others = V_{IH}/V_{IL}
	HM62256B-5	I _{CC1}	_		60		
	HM62256B-7	I _{CC1}	_	33	60		
	HM62256B-8	I _{CC1}	_	29	50		
		I _{CC2}	_	5	15	mA	Cycle time = 1 μ s, $I_{I/O}$ = 0 mA \overline{CS} = V_{IL} , V_{IH} = V_{CC} , V_{IL} = 0
Standby power supply current		I _{SB}	_	0.3	2	mA	CS = V _{IH}
		I _{SB1}	_	0.2	100	μΑ	$Vin \geq 0 \ V, \ \overline{CS} \geq V_{CC} - 0.2 \ V,$
			_	0.2*2	50 ^{*2}		
				0.2*3	10 ^{*3}		
Output low voltage		V _{OL}	_		0.4	V	I _{OL} = 2.1 mA
Output high voltage		V_{OH}	2.4	_	_	V	$I_{OH} = -1.0 \text{ mA}$

Notes: 1. Typical values are at $V_{CC} = 5.0 \text{ V}$, $Ta = +25^{\circ}\text{C}$ and not guaranteed.

- 2. This characteristics is guaranteed only for L-SL version.
- 3. This characteristics is guaranteed only for L-UL version.

Capacitance (Ta = 25° C, f = 1.0 MHz)^{*1}

Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
Input capacitance*1	Cin	_	_	8	pF	Vin = 0 V
Input/output capacitance*1	C _{I/O}	_	_	10	pF	V _{I/O} = 0 V

Note: 1. This parameter is sampled and not 100% tested.

AC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V ± 10%, unless otherwise noted.)

Test Conditions

• Input pulse levels: 0.8 V to 2.4 V

• Input rise and fall times: 5 ns

• Input and output timing reference level: 1.5 V

• Output load: HM62256B-4: 1 TTL Gate + C_L (30 pF)(Including scope & jig)

$$\begin{split} &HM62256B\text{-}5\text{:} \quad 1 \text{ TTL Gate} + C_{\text{L}}(50 \text{ pF}) \text{(Including scope \& jig)} \\ &HM62256B\text{-}7/8\text{:} \quad 1 \text{ TTL Gate} + C_{\text{L}} \ (100 \text{ pF}) \text{(Including scope \& jig)} \end{split}$$

Read Cycle

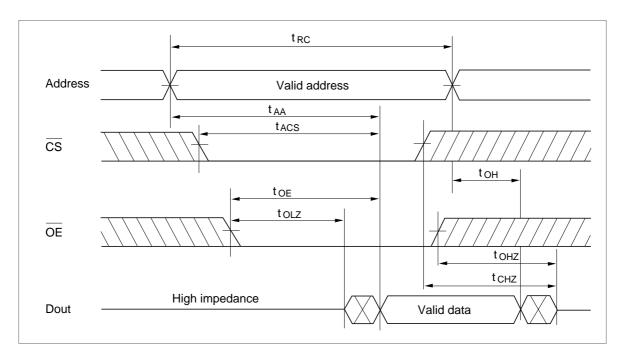
HM62256B

		-4		-5		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Read cycle time	t _{RC}	45	_	55	_	70	_	85	_	ns	
Address access time	t _{AA}	_	45	_	55	_	70	_	85	ns	
Chip select access time	t _{ACS}	_	45	_	55	_	70	_	85	ns	
Output enable to output valid	t _{oe}		30	_	35	_	40	_	45	ns	
Chip selection to output in low-Z	t _{CLZ}	5	_	5	_	10	_	10	_	ns	2
Output enable to output in low-Z	t _{OLZ}	5	_	5	_	5	_	5	_	ns	2
Chip deselection in to output in high-Z	t _{CHZ}	0	20	0	20	0	25	0	30	ns	1, 2
Output disable to output in high-Z	t _{OHZ}	0	20	0	20	0	25	0	30	ns	1, 2
Output hold from address change	t _{oh}	5	_	5	_	5	_	10	_	ns	

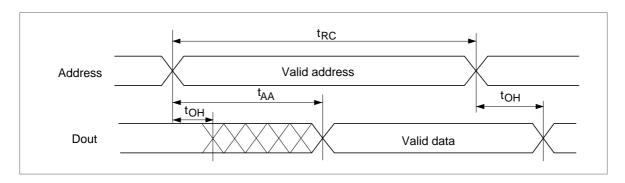
Notes: 1. t_{CHZ} and t_{OHZ} defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

2. This parameter is sampled and not 100% tested.

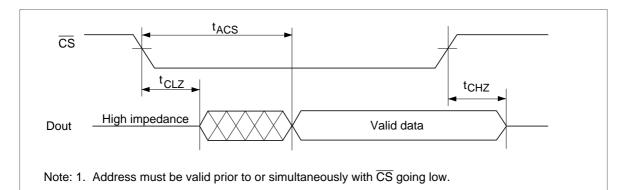
Read Timing Waveform (1) $(\overline{WE}=V_{IH})$



Read Timing Waveform (2) $(\overline{WE}{=}V_{IH},\,\overline{CS}{=}V_{IL},\,\overline{OE}{=}V_{IL})$



Read Timing Waveform (3) $(\overline{WE} = V_{IH}, \overline{OE} = V_{IL})^{*1}$



Write Cycle

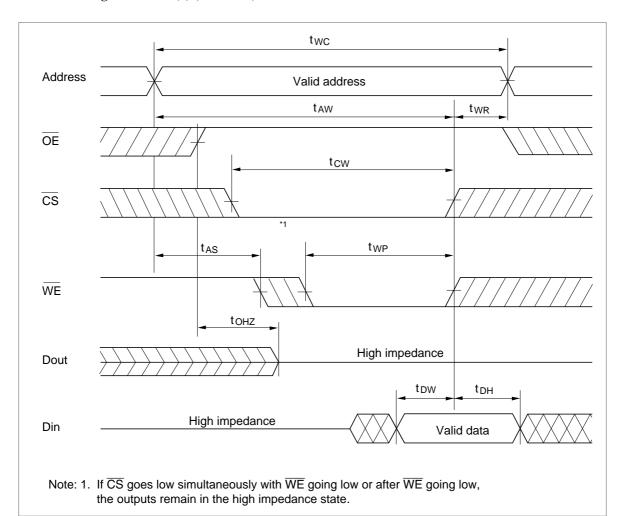
HM62256B

		-4		-5		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write cycle time	t _{wc}	45	_	55	_	70	_	85	_	ns	
Chip selection to end of write	t _{cw}	35	_	40	_	60	_	75	_	ns	4
Address setup time	t _{AS}	0	_	0	_	0	_	0	_	ns	5
Address valid to end of write	t _{AW}	35	_	40	_	60	_	75	_	ns	
Write pulse width	t _{wP}	30	_	35	_	50	_	55	_	ns	3, 8
Write recovery time	t _{wR}	0	_	0	_	0	_	0	_	ns	6
WE to output in high-Z	t _{whz}	0	20	0	20	0	25	0	40	ns	1, 2, 7
Data to write time overlap	t _{DW}	20	_	25	_	30	_	35	_	ns	•
Data hold from write time	t _{DH}	0	_	0	_	0	_	0	_	ns	
Output active from end of write	t _{ow}	5	_	5	_	5	_	5	_	ns	2
Output disable to output in high-Z	t _{OHZ}	0	20	0	20	0	25	0	40	ns	1, 2, 7

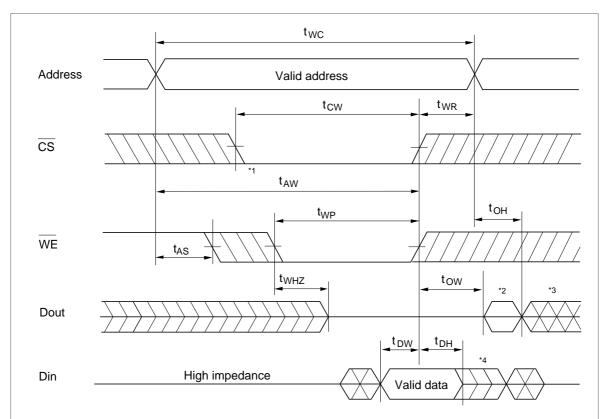
Notes: 1. t_{OHZ} and t_{WHZ} are defined as the time at which the outputs achieve the open circuit conditions and are not referred to output voltage levels.

- 2. This parameter is sampled and not 100% tested.
- 3. A write occurs during the overlap (t_{WP}) of a low \overline{CS} and a low \overline{WE} . A write begins at the later transition of \overline{CS} going low or \overline{WE} going low. A write ends at the earlier transition of \overline{CS} going high or \overline{WE} going high. t_{WP} is measured from the beginning of write to the end of write.
- 4. t_{cw} is measured from $\overline{\text{CS}}$ going low to the end of write.
- 5. $\,t_{\mbox{\tiny AS}}$ is measured from the address valid to the beginning of write.
- 6. t_{wR} is measured from the earlier of \overline{WE} or \overline{CS} going high to the end of write cycle.
- 7. Durng this period, I/O pins are in the output state so that the input signals of the opposite phase to the outputs must not be applied.
- 8. In the write cycle with $\overline{\text{OE}}$ low fixed, t_{WP} must satisfy the following equation to avoid a problem of data bus contention, $t_{\text{WP}} \ge t_{\text{WHZ}}$ max + t_{DW} min.

Write Timing Waveform (1) $(\overline{OE} \text{ Clock})$



Write Timing Waveform (2) (\overline{OE} Low Fixed) (\overline{OE} = $V_{\rm IL}$)



Notes: 1. If $\overline{\text{CS}}$ goes low simultaneously with $\overline{\text{WE}}$ going low or after $\overline{\text{WE}}$ going low, the outputs remain in the high impedance state.

- 2. Dout is the same phase of the write data of this write cycle.
- 3. Dout is the read data of next address.
- 4. If $\overline{\text{CS}}$ is low during this period, I/O pins are in the output state. Therefore, the input signals of the opposite phase to the output must not be applied to them.

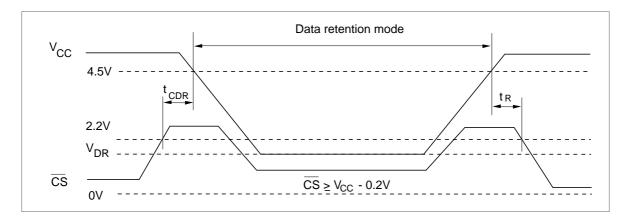
Low V_{CC} **Data Retention Characteristics** (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ*1	Max	Unit	Test Conditions ^{*6}
V _{cc} for data retention	V_{DR}	2.0	_	5.5	V	$\overline{\text{CS}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V},$ $\text{Vin } \ge 0 \text{ V}$
Data retention current	I _{CCDR}	_	0.05	30*2	μΑ	V _{CC} = 3.0 V, Vin ≥ 0 V
		_	0.05	10*3		$\overline{\text{CS}} \ge V_{\text{CC}} - 0.2 \text{ V},$
		_	0.05	3*4		
Chip deselect to data retention time	t _{CDR}	0			ns	See retention waveform
Operation recovery time	t _R	t _{RC} *5	_	_	ns	

Notes: 1. Typical values are at $V_{cc} = 3.0 \text{ V}$, $Ta = 25^{\circ}\text{C}$ and not guaranteed.

- 2. $10 \mu A \text{ max at Ta} = 0 \text{ to} + 40^{\circ} \text{C}.$
- 3. This characteristics guaranteed for only L-SL version. 3 μ A max at Ta = 0 to +40°C.
- 4. This characteristics guaranteed for only L-UL version. $0.6 \,\mu\text{A}$ max at Ta = 0 to +40°C.
- 5. t_{RC} = read cycle time.
- 6. $\overline{\text{CS}}$ controls address buffer, $\overline{\text{WE}}$ buffer, $\overline{\text{OE}}$ buffer, and Din buffer. If $\overline{\text{CS}}$ controls data retention mode, other input levels (address, $\overline{\text{WE}}$, $\overline{\text{OE}}$, I/O) can be in the high impedance state.

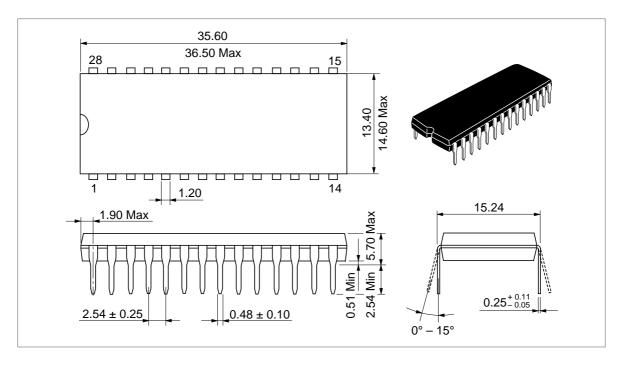
Low V_{CC} Data Retention Timing Waveform



Package Dimensions

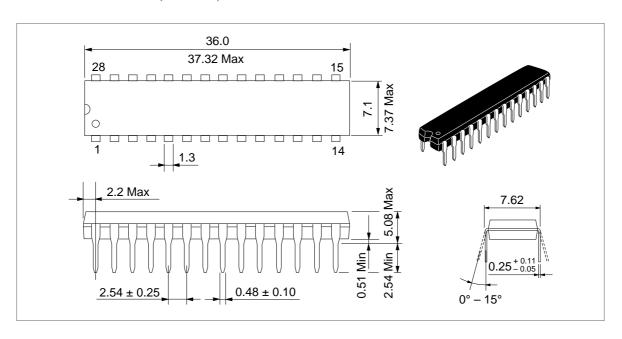
HM62256BLP Series (DP-28)

Unit: mm



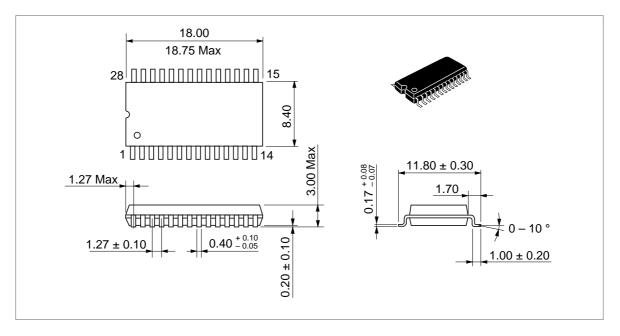
HM62256BLSP Series (DP-28NA)

Unit: mm



HM62256BLFP Series (FP-28DA)

Unit: mm



HM62256BLT Series (TFP-32DA)

Unit: mm

